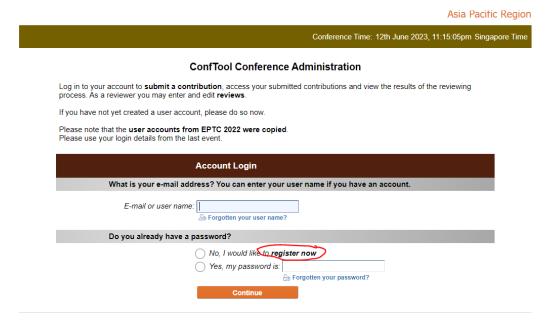
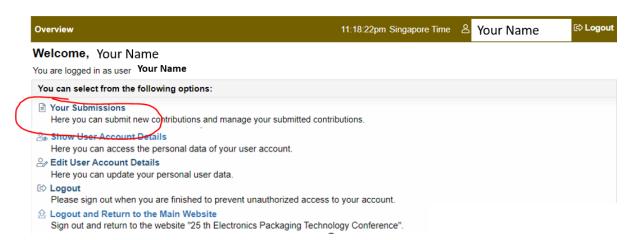
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To submit an abstract for EPTC 2023, please follow these steps:

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- 3. Look for the link labelled "Abstract Submission" and click on it.
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Advanced Optoelectronics and Displays

Design, simulation, interconnection, packaging, integration and materials for optoelectronics and novel displays - micro/mini/nano LED, foldable and flexible displays, augmented reality and virtual reality and wearable displays. Silicon and III-V photonics; optical sensors, interconnects, interposers, quantum device packaging; photonics SiP; free-space optical communications, waveguide; automotive photonics, 3D sensing; optoelectronic fiber coupling assembly, materials and reliability; fiber optic transceivers, electro-optical integration.

Deadline: 15th June 2023, 11:59:59pm Singapore Time, Time left: 3 days 0 hours

Advanced Packaging

Flip-chip, 2.5D & 3D, embedded passives & actives on substrates, chiplets, system in packaging, embedded chip packaging technologies, panellevel packaging, RF, microwave & millimeter-wave, power and rugged electronics packaging. Advanced packaging solutions for 5G, IoT, cloud computing, autonomous vehicles, antennas, sensors, power transfer, EM shielding, RF to THz communications.

Deadline: 15th June 2023, 11:59:59pm Singapore Time, Time left: 3 days 0 hours

Assembly and Manufacturing Technology

Embedded/hybrid package manufacturing processes; warpage control and management in board-level assembly; thin die/package handling and assembly advance in flexible and printed electronics manufacturing Large/ultra-large package (SiP, SIM, MCP) integration and manufacturing; thermally enhanced packaging and assembly challenges. Additive manufacturing. Panel-level manufacturing and assembly. Heterogeneous integration and manufacturing.

Deadline: 15th June 2023, 11:59:59pm Singapore Time, Time left: 3 days 0 hours

► Electrical Simulations & Characterization

Power plane modeling, Signal integrity analysis by simulations and characterization, 2D/2.5D/3D package level high-speed signal design, Characterization and test methodologies.

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► Emerging Technologies

Novel and unique packaging and material technologies for soft and intelligent packaging, flexible hybrid electronics, implantable biosensors and bioelectronics, packaging for extreme harsh environment, green/bio-resorbable packaging; packaging of MEMS & NEMS, packaging for wide bandgap devices, quantum computing, packaging sensing and communication.

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▶ Interconnection Technologies

Au/Ag/Cu/Al Wire-bond / Wedge bond technology, Flip-chip & Cu pillar, Solder alternatives, Cu to Cu, wafer-level bonding & die attachment (Pbfree), Fan-out, panel-level, chiplets, SiP, micro-bump, high I/O thermo-compression/hybrid bonding, fine-pitch/multi-layer RDL, printable interconnects, conductive/ nonconductive adhesives, low-temperature solder, interconnects design and technology for emerging applications.

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Materials and Processing

Photoresist, polymer dielectrics, solder, die-attach, underfill, substrates, lead-frames, materials for wafer & panel-level packaging; harsh environments; wafer bonding/ debond materials; emerging electronic materials & processes; novel solder metallurgies; molding compounds; thermal interface materials; advanced wire-bonding, conductive adhesives. PCB for advanced packaging, assembly processes using newer materials. Substrates in the large/ultra-large package (SiP, SIM, MCP) integration

Deadline: 15th June 2023, 11:59:59pm Singapore Time, Time left: 3 days 0 hours

► Mechanical Simulation & Characterization

Thermal-mechanical interaction, moisture, fracture, fatigue, dynamic impact modelling and characterization. process modelling, etc.

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▶ Quality, Reliability & Fallure Analysis

Silicon, component, board and system-level reliability assessment, Interfacial adhesion, Accelerated testing, Failure characterization.

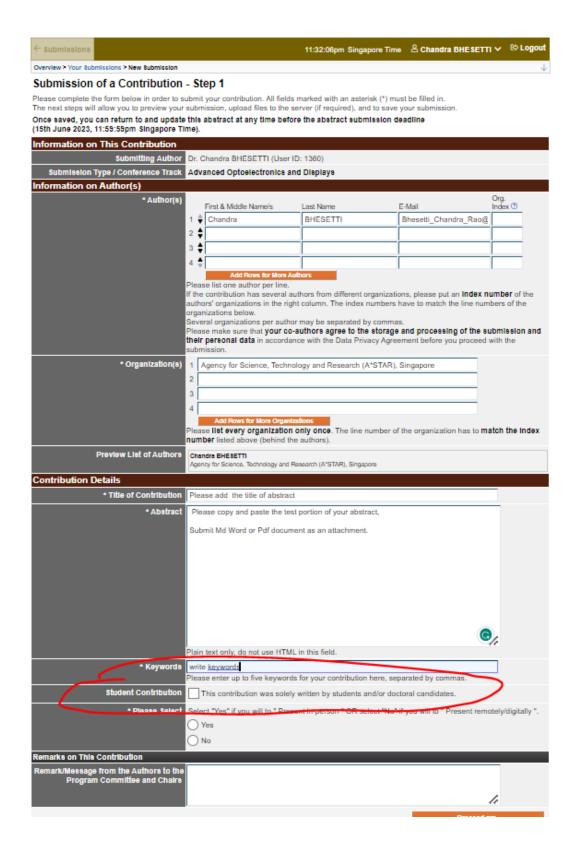
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Smart Manufacturing and Equipment Technology

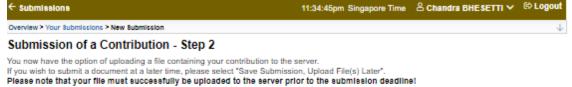
Smart Manufacturing in packaging, cycle time, data analytics, advanced metrology, machine learning, artificial intelligence, advanced equipment for assembly, packaging and handling Digital Twin and process simulation.

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- 8. After selecting the relevant technical topic, you will be directed to the abstract submission page.
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